AT28BV64

Features

- 2.7V to 3.6V Supply Full Read and Write Operation
- Low Power Dissipation 8 mA Active Current 50 μA CMOS Standby Current
- Read Access Time 300 ns
- Byte Write 3 ms
- Direct Microprocessor Control
 DATA Polling
 READY/BUSY Open Drain Output
- High Reliability CMOS Technology Endurance: 100,000 Cycles Data Retention: 10 Years
- JEDEC Approved Byte-Wide Pinout
- Commercial and Industrial Temperature Ranges

Description

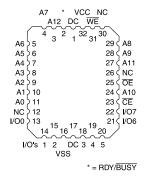
The AT28BV64 is a low-voltage, low-power Electrically Erasable and Programmable Read Only Memory specifically designed for battery powered applications. Its 64K of memory is organized 8,192 words by 8 bits. Manufactured with Atmel's advanced nonvolatile CMOS technology, the device offers access times to 200 ns with power dissipation less than 30 mW. When the device is deselected the standby current is less than 50 μ A.

The AT28BV64 is accessed like a Static RAM for the read or write cycles without the need for external components. During a byte write, the address and data are latched internally, freeing the microprocessor address and data bus for other operations. Fol-(continued)

Pin Configurations

| Pin Name | Function |
|-------------|---------------------|
| A0 - A12 | Addresses |
| CE | Chip Enable |
| OE | Output Enable |
| WE | Write Enable |
| I/O0 - I/O7 | Data Inputs/Outputs |
| RDY/BUSY | Ready/Busy Output |
| NC | No Connect |
| DC | Don't Connect |

PLCC Top View



PDIP, SOIC Top View RDY/BUSY 28 0 VCC 1 27 🗅 WE A12 🗆 2 A7 🗖 3 26 🗆 NC A6 🗆 4 25 🗆 A8 A5 🗆 5 24 🗆 A9 A4 🗆 6 23 🗅 A11 A3 🗆 7 A2 🗆 8 21 🗅 A10 A1口 9 A0 🗖 10 19 1/07 1/00 1 11 18 1/06 1/01 1 12 17 11/05 1/02 1 13 16 1/04 GND d 14 15 1/03

TSOP Top View

| A11 A8 | OE A9 | 1 3 | 26 | A10 | CE I/O6 |
|-----------|-----------|---------|------|------------|------------|
| WE | NC VCC | 5 7 | 24 | | /04 |
| RDY/BUSY | A12 | , 9 | 20 | | GND |
| A7 A5 | A6 | 2 11 | 18 . | 19 I/O0 | I/O1 A0 |
| A3 | A4 | 13 4 | 16 | 15 A1 | A2 |

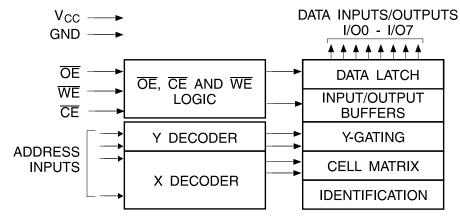
64K (8K x 8) *Battery-Voltage*[™] CMOS E²PROM





Description (Continued)

lowing the initiation of a write cycle, the device will go to a busy state and automatically clear and write the latched data using an internal control timer. The device includes two methods for <u>detecting</u> th<u>e end</u> of a write cycle, level detection of RDY/BUSY and DATA polling of I/O₇. Once the end of a write cycle has been detected, a new access for a read or write can begin. Atmel's 28BV64 has additional features to ensure high quality and manufacturability. The device utilizes error correction internally for extended endurance and for improved data retention characteristics. An extra 32-bytes of E^2 PROM are available for device identification or tracking.



Block Diagram

Absolute Maximum Ratings*

| Temperature Under Bias55°C to +125°C |
|---|
| Storage Temperature65°C to +150°C |
| All Input Voltages (including NC Pins) with Respect to Ground0.6V to +6.25V |
| All Output Voltages with Respect to Ground0.6V to V _{CC} + 0.6V |
| Voltage on $\overline{\text{OE}}$ and A9 with Respect to Ground0.6V to +13.5V |

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Device Operation

READ: The <u>AT28BV64</u> is accessed like a Static RAM. When CE and OE are low and WE is high, the data stored at the memory location determined by the address pins is asserted on the outputs. <u>The outputs are put in a high im-</u> pedance state whenever CE or OE is high. This dual line control gives designers increased flexibility in preventing bus contention.

BYTE WRITE: Writing data into the AT28BV64 is similar to writing into a Static RAM. A low pulse on the WE or CE input with \overline{OE} high and \overline{CE} or WE low (respectively) initiates a byte write. The address location is latched on the falling edge of WE (or \overline{CE}); the new data is latched on the rising edge. Internally, the device performs a self-clear before write. Once a byte write has been started, it will automatically time itself to completion. Once a programming operation has been initiated and for the duration of twc, a read operation will effectively be a polling operation.

READY/BUSY: Pin 1 is an open drain READY/BUSY output that can be used to detect the end of a write cycle. RDY/BUSY is actively pulled low during the write cycle and is released at the completion of the write. The open drain connection allows for OR-tying of several devices to the same RDY/BUSY line.

DATA POLLING: The AT28BV64 provides DATA POLLING to signal the completion of a write cycle. During a write cycle, an attempted read of the data being written results in the complement of that data for I/O₇ (the other outputs are indeterminate). When the write cycle is finished, true data appears on all outputs.

WRITE PROTECTION: Inadvertent writes to the device are protected against in the following ways. (a) V_{CC} sense— if V_{CC} is below 1.8V (typical) the write function is inhibited. (b) V_{CC} power on delay— once V_{CC} has reached 2.0V the device will automatically time out 10 ms (typical) before allowing a byte write. (c) Write Inhibit— holding any one of OE low, CE high or WE high inhibits byte write cycles.





DC and AC Operating Range

| | | AT28BV64-30 |
|--------------------|------|--------------|
| Operating | Com. | 0°C - 70°C |
| Temperature (Case) | Ind. | -40°C - 85°C |
| Vcc Power Supply | | 2.7V to 3.6V |

Operating Modes

| Mode | CE | OE | WE | I/O | |
|-----------------------|-----|------------------|-----|-----------------|--|
| Read | VIL | VIL | VIH | Dout | |
| Write ⁽²⁾ | VIL | VIH | VIL | D _{IN} | |
| Standby/Write Inhibit | Vін | X ⁽¹⁾ | Х | High Z | |
| Write Inhibit | Х | Х | VIH | | |
| Write Inhibit | Х | VIL | Х | | |
| Output Disable | Х | VIH | Х | High Z | |

Notes: 1. X can be V_{IL} or V_{IH} . 2. Refer to AC Programming Waveforms.

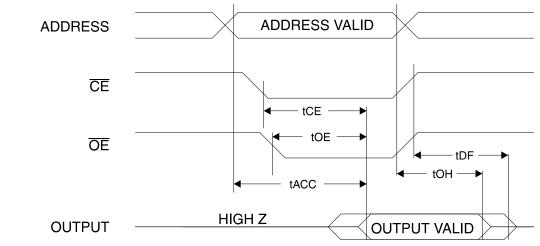
DC Characteristics

| Symbol | Parameter | Condition | Min | Max | Units |
|--------|-----------------------------------|--|-----|-----|-------|
| ILI | Input Load Current | $V_{IN} = 0V$ to $V_{CC} + 1.0V$ | | 5 | μA |
| ILO | Output Leakage Current | $V_{I/O} = 0V$ to V_{CC} | | 5 | μA |
| ISB | Vcc Standby Current CMOS | $\overline{CE} = V_{CC} - 0.3V$ to $V_{CC} + 1.0V$ | | 50 | μA |
| Icc | V _{CC} Active Current AC | f = 5 MHz; I_{OUT} = 0 mA; CE = V _{IL} | | 8 | mA |
| VIL | Input Low Voltage | | | 0.6 | V |
| VIH | Input High Voltage | | 2.0 | | V |
| Mai | | I _{OL} = 1 mA | | 0.3 | V |
| Vol | Output Low Voltage | $I_{OL} = 2 \text{ mA for RDY}/\overline{\text{BUSY}}$ | | 0.3 | V |
| Vон | Output High Voltage | Іон = -100 μА | 2.0 | | V |

AC Read Characteristics

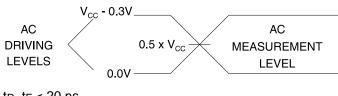
| | | AT28B | V64-30 | |
|-----------------------------------|---|-------|--------|-------|
| Symbol | Parameter | Min | Max | Units |
| tACC | Address to Output Delay | | 300 | ns |
| tce ⁽¹⁾ | CE to Output Delay | | 300 | ns |
| toe (2) | OE to Output Delay | 0 | 150 | ns |
| t _{DF} ^(3, 4) | \overline{CE} or \overline{OE} High to Output Float | 0 | 60 | ns |
| tон | Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first | 0 | | ns |

AC Read Waveforms ^(1, 2, 3, 4)



- Notes: 1. \overline{CE} may be delayed up to t_{ACC} t_{CE} after the address transition without impact on tACC.
 - 2. OE may be delayed up to tCE tOE after the falling edge of \overline{CE} without impact on t_{CE} or by t_{ACC} - t_{OE} after an address change without impact on tACC.

Input Test Waveforms and Measurement Level

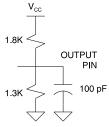


t_R, t_F < 20 ns

V_{cc}

Output Test Load

 $(C_{L} = 5 \text{ pF}).$



3. t_{DF} is specified from \overline{OE} or \overline{CE} whichever occurs first

4. This parameter is characterized and is not 100% tested.

Pin Capacitance (f = 1 MHz, T = 25° C)⁽¹⁾

| | Тур | Max | Units | Conditions |
|------|-----|-----|-------|----------------|
| CIN | 4 | 6 | pF | $V_{IN} = 0V$ |
| Cout | 8 | 12 | pF | $V_{OUT} = 0V$ |

Note: 1. This parameter is characterized and is not 100% tested.



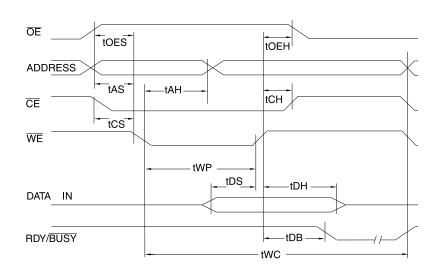


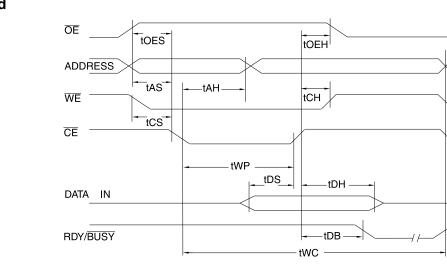
AC Write Characteristics

| Symbol | Parameter | Min | Max | Units |
|------------------------------------|--|-----|------|-------|
| t _{AS} , t _{OES} | Address, OE Set-up Time | 10 | | ns |
| tан | Address Hold Time | 100 | | ns |
| t _{WP} | Write Pulse Width (\overline{WE} or \overline{CE}) | 150 | 1000 | ns |
| t _{DS} | Data Set-up Time | 100 | | ns |
| tDн, tOEH | Data, OE Hold Time | 10 | | ns |
| t _{DB} | Time to Device Busy | | 50 | ns |
| twc | Write Cycle Time | | 3 | ms |

AC Write Waveforms

WE Controlled





AT28BV64

CE Controlled

AT28BV64

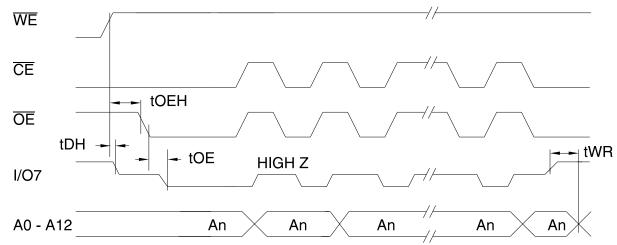
Data Polling Characteristics (1)

| Symbol | Parameter | Min | Тур | Max | Units |
|-----------------|-----------------------------------|-----|-----|-----|-------|
| tDH | Data Hold Time | 10 | | | ns |
| tоен | OE Hold Time | 10 | | | ns |
| tOE | OE to Output Delay ⁽²⁾ | | | | ns |
| t _{WR} | Write Recovery Time | 0 | | | ns |

Notes: 1. These parameters are characterized and not 100% tested.

2. See AC Read Characteristics.

Data Polling Waveforms







Ordering Information ⁽¹⁾

| tACC | Icc (mA) | | Operating | Ordering Code | Dealarm | |
|------|----------|---------|--------------|--|---------------------------|-------------------------------|
| (ns) | Active | Standby | Valte ve | Ordering Code | Package | Operation Range |
| 300 | 8 | 0.05 | 2.7V to 3.6V | AT28BV64-30JC AT28BV64-30PC AT28BV64-30SC AT28BV64-30TC | 32J 28P6 28S 28T | Commercial (0°C to 70°C) |
| | 8 | 0.05 | 2.7V to 3.6V | AT28BV64-30JI AT28BV64-30PI AT28BV64-30SI AT28BV64-30TI | 32J 28P6 28S 28T | Industrial (-40°C to 85°C) |

Note: 1. See Valid Part Number table below.

Valid Part Numbers

The following table lists standard Atmel products that can be ordered.

| Device Numbers | Speed | Package and Temperature Combinations |
|----------------|-------|--------------------------------------|
| AT28BV64 | 30 | JC, JI, PC, PI, SC, SI, TC, TI |

| Package Type | |
|--------------|---|
| 32J | 32 Lead, Plastic J-Leaded Chip Carrier (PLCC) |
| 28P6 | 28 Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP) |
| 28S | 28 Lead, 0.300" Wide, Plastic Gull Wing, Small Outline (SOIC) |
| 28T | 28 Lead, Plastic Thin Small Outline Package (TSOP) |

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Datasheets for electronic components.